

CMP SLURRY ADDITIVE FOR FOREIGN MATTER DETECTION

ABSTRACT

A method and structure polishes and cleans silicon wafers by mixing a marker with a slurry to form a slurry mixture, performs chemical mechanical polishing on a silicon wafer using the slurry mixture, rinses the slurry mixture from the silicon wafer, checks the silicon wafer for marker residue, and repeats the rinsing process if the checking process detects the marker residue on the wafer.